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SUZUKI et al.(10) **Pub. No.: US 2023/0230862 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **SUBSTRATE TRANSPORT METHOD AND
SUBSTRATE PROCESSING SYSTEM**(52) **U.S. Cl.**CPC .. *H01L 21/67201* (2013.01); *H01L 21/67742*
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(57)

ABSTRACT

A substrate transport method is employed in a substrate processing system including a plurality of processing chambers, a load lock chamber, a vacuum transport device provided in a vacuum transport chamber connecting the load lock chamber and the plurality of processing chambers and configured to simultaneously transport a plurality of substrates, and an atmospheric transport device provided in an atmospheric transport chamber and configured to transport a substrate from a carrier to the load lock chamber. The substrate transport method includes acquiring in advance a relative positional error for a case where the plurality of substrates are transported from the load lock chamber to the plurality of processing chambers and placed on a stage in the plurality of processing chambers, and placing the plurality of substrates on a stage in the load lock chamber, based on a transport path of the plurality of substrates and the relative positional error.

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